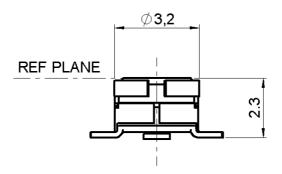
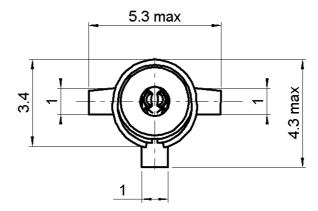
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Series: MMS







Scale 1/1

All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	PHOSPHOR BRONZE BERYLLIUM COPPER PHOSPHOR BRONZE PTFE	.GOLD 0.2 OVER NICKEL 2 GOLD 0.2 OVER TIN NICKEL 2 .GOLD 0.2 OVER NICKEL 2

Issue: 0743 A

In the effort to improve our products, we reserve the right to make changes judged to be



STRAIGHT FEMALE RECEPTACLE FOR PCB

SMT TYPE REEL PACKAGING BY 100

R209.408.012

Series: MMS

PACKAGING

Standard	Unit	Other	
100	'W' option	Contact us	

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance 50Ω Frequency 0-6 GH

VSWR * + 0,0000 x F(GHz) Maxi Insertion loss ** $\sqrt{F(GHz)}$ dB Maxi

RF leakage - (NA - F(GHz)) dB mini
Voltage rating 50 Veff Maxi

Dielectric withstanding voltage Insulation resistance 250 Veff mini 500 M Ω mini

ENVIRONMENTAL

Operating temperature -40/+125 ° C

Hermetic seal **NA** Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

*1.2 à 2GHz/Avg 1,07 **Max 0.07/Avg 0.06

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

NA N mini
NA N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 50 Cycles mini

Weight **0,0300** g

Issue: 0743 A

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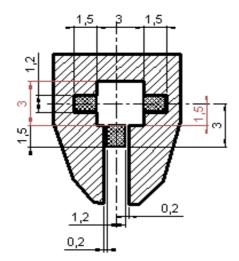
Series: MMS

MMS SERIES – INFORMATION

Coplanar line: Ground and signal are on the same side. Thicknass of PCB: 1mm

The material of PCB is glass-epoxy composite. (Er = 4.8)

The sold er resist should be printed except for the land pattern on the PCB.



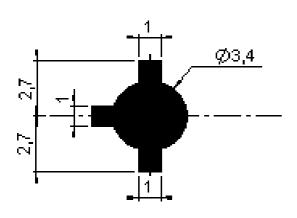


Pattern

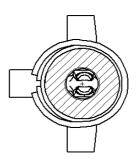


Land for solder paste

SHADOW OF MMS RECEPTACLE FOR VIDEO CAMERA



ASPIRATION AREA





ASPIRATION AREA

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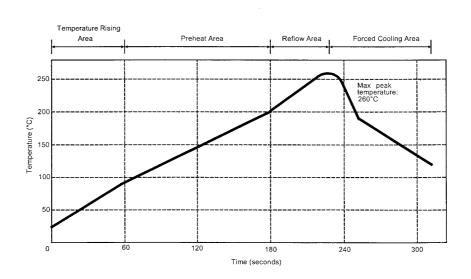
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SOLDER PROCEDURE

- Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 micromm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
- 3. Soldering by infra-red reflow.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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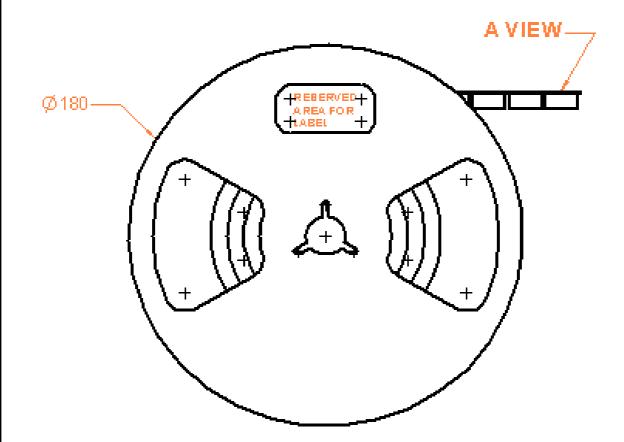
In the effort to improve our products, we reserve the right to make changes judged to be

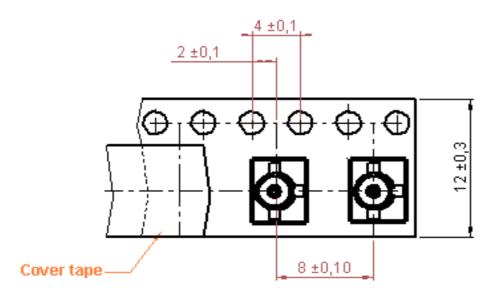
necessary.



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A VIEW (scale: 4)

Issue: 0743 A

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